TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type

# SSM3J108TU

#### **High Speed Switching Applications**

• 1.8V drive

• Low on-resistance:  $R_{on} = 363 \text{m}\Omega \text{ (max) (@V_{GS} = -1.8 V)}$ 

 $R_{on} = 230 m\Omega \text{ (max) (@V_{GS} = -2.5 V)}$ 

 $R_{on} = 158m\Omega \text{ (max) (@V_{GS} = -4.0 V)}$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteris	tic	Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	-20	V	
Gate-Source voltage		V <sub>GSS</sub>	± 8	V ((	
Drain current	DC	I <sub>D</sub>	-1.8	A	
Drain current	Pulse	I <sub>DP</sub>	-3.6		
Drain power dissipation		P <sub>D (Note 1)</sub>	800	(mw)	
Drain power dissipation	ı	P <sub>D (Note 2)</sub>	500	VIIIVV	
Channel temperature		T <sub>ch</sub>	150	ပွ	
Storage temperature ra	inge	T <sub>stg</sub>	-55 to 150	°C	

Note:

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on ceramic board.

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 0.8 \text{ mm}, \text{Cu Pad: } 645 \text{ mm}^2)$ 

Note 2: Mounted on FR4 board.

(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 645 mm<sup>2</sup>)

#### 2.1±0.1 1.7±0.1 1.7±0.1 1.00-1 1.0

Weight: 6.6 mg (typ.)

#### Electrical Characteristics (Ta = 25°C)

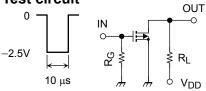
Charact	eristic	Symbol	Test Conditions		Min	Тур.	Max	Unit	
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$		-20	_	_	V	
		V (BR) DSX	$I_D = -1 \text{ mA}, V_{GS} = +8 \text{ V}$	-12	_	_	v		
Drain cut-off curren	Ĭ.	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0$				-10	μΑ	
Gate leakage curre	nt	IGSS	$V_{GS} = \pm 8V, V_{DS} = 0$				±1	μΑ	
Gate threshold volta	age	V <sub>th</sub>	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$		-0.3	_	-1.0	V	
Forward transfer ad	Imittance	Yfs	$V_{DS} = -3 \text{ V}, I_{D} = -0.8 \text{ A}$	(Note3)	1.9	3.2	_	S	
Drain-Source on-resistance			$I_D = -0.8 \text{ A}, V_{GS} = -4.0 \text{ V}$	(Note3)	_	125	158	mΩ	
		R <sub>DS</sub> (ON)	$I_D = -0.4 \text{ A}, V_{GS} = -2.5 \text{ V}$	(Note3)	_	170	230		
		$\overline{}$	$I_D = -0.1 \text{ A}, V_{GS} = -1.8 \text{ V}$	(Note3)	_	230	363		
Input capacitance		C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ I}$	ИНz	_	250	_	pF	
Output capacitance		Coss	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	45	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	35	_	pF	
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = -10 \text{ V}, I_D = -0.25 \text{ A},$ $V_{GS} = 0 \text{ to } -2.5 \text{ V}, R_G = 4.7 \Omega$		_	12	_	ns	
	Turn-off time	t <sub>off</sub>			_	18	_		
Drain-Source forward voltage		V <sub>DSF</sub>	I <sub>D</sub> = 1.8A, V <sub>GS</sub> = 0 V	(Note3)	_	0.85	1.2	V	

Note3: Pulse test

Start of commercial production 2005-02

#### **Switching Time Test Circuit**

(a) Test circuit



 $V_{DD} = -10 \text{ V}$ 

 $R_G = 4.7 \Omega$ 

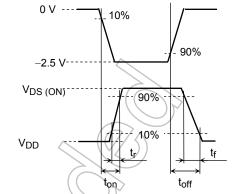
Duty ≤ 1%

 $V_{IN}$ :  $t_r$ ,  $t_f < 5$  ns Common Source

Ta = 25°C

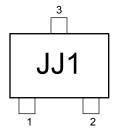
(b) V<sub>IN</sub>

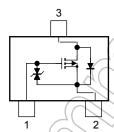
(c) Vout



#### Marking

#### **Equivalent Circuit (top view)**





#### **Precaution**

 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$ =-1mA for this product. For normal switching operation,  $V_{GS}$  (on) requires a higher voltage than  $V_{th}$ , and  $V_{GS}$  (off) requires a lower voltage than  $V_{th}$ .

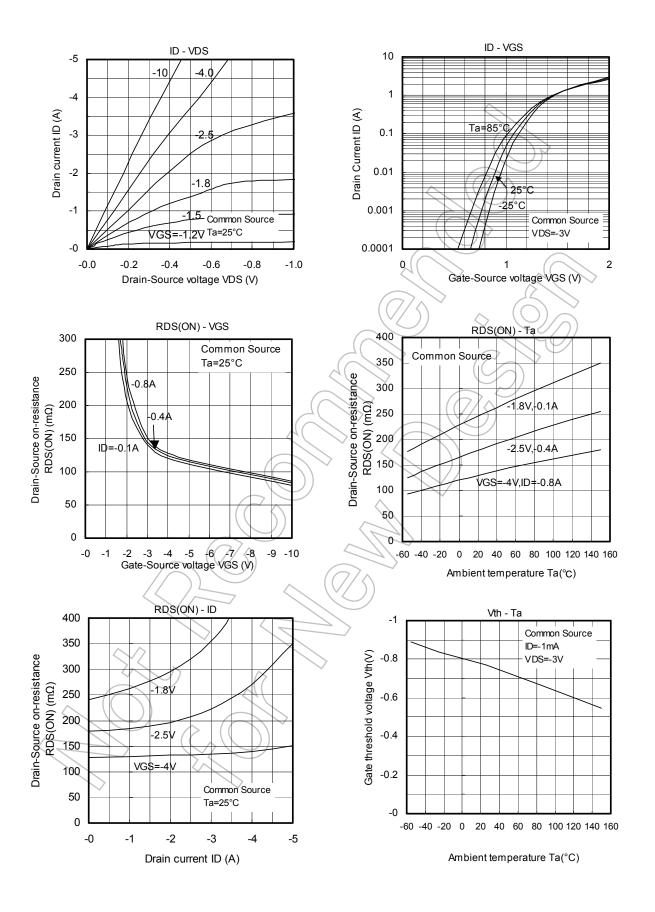
(The relationship can be established as follows: VGS (off) < Vth < VGS (on))

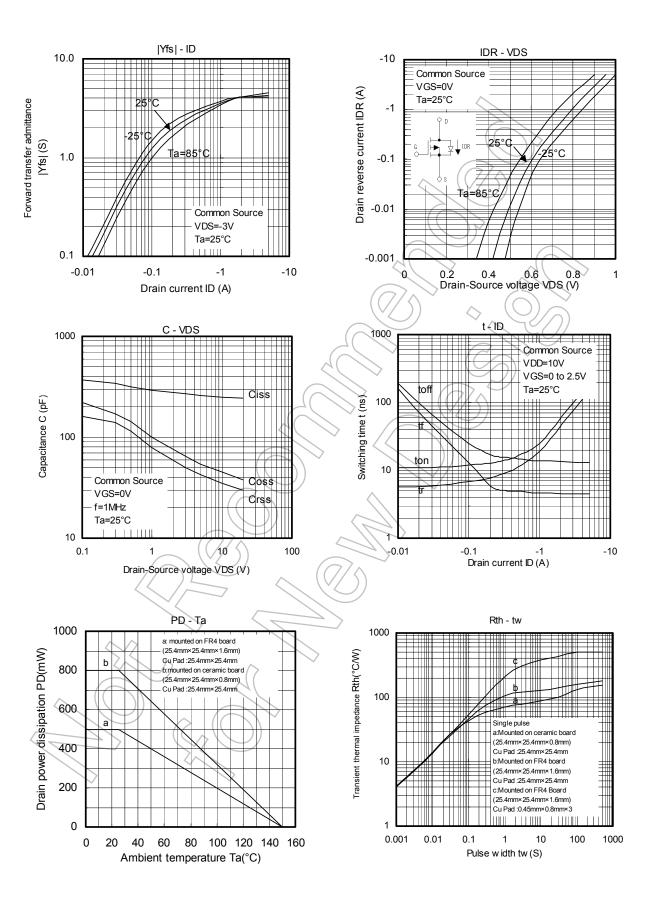
Take this into consideration when using the device.

#### **Handling Precaution**

When handling individual devices which are not yet mounted on a circuit board, be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

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